

### **REMARKS**

Claims 15, 16, 21 – 23, and 25-34 are now pending in the application. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

### **SPECIFICATION**

The specification stands objected to for certain informalities. Applicant has provided a Substitute Specification, excluding the claims, for the Examiner's review as required by the Examiner. Applicant has also provided a marked-up version of the specification, excluding the claims, that highlights each of the amendments made to the specification. No new matter has been added. Favorable consideration of the Substitute Specification is respectfully requested.

### **REJECTION UNDER 35 U.S.C. § 102**

Claims 15, 21, 23, 28 and 32 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Uchiyama (U.S. Pat. No. 6,265,770 B1). This rejection is respectfully traversed.

Claims 15 and 21 have been amended to call for the thermocompression-bonding to be performed with a compression bonding head. Claims 15 and 21 have also been amended to call for the band region to be wider than the head. Uchiyama does not anticipate such a method. Specifically, Uchiyama does not disclose a band region that is wider than a thermocompression-bonding head. Since this element of the claims is not disclosed by Uchiyama, the claimed invention of independent claims 15

and 21, and their corresponding dependent claims, is not anticipated. As such, reconsideration and withdrawal of this rejection is respectfully requested.

#### **REJECTION UNDER 35 U.S.C. § 103**

Claims 16, 22, 24 – 27 and 29 - 31 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Uchiyama (U.S. Pat. No. 6,265,770 B1). This rejection is respectfully traversed.

Claims 16, 22, 24-27, and 29-31 are dependent on either claim 15 or claim 21, addressed above. Since these claims are dependent on claims 15 and 21, which are not anticipated in view of Uchiyama, these claims would not have been obvious. As such, reconsideration and withdrawal of this rejection is respectfully requested.

#### **NEW CLAIMS**

New claims 33 and 34 have been added. These claims are supported throughout the specification and drawings as originally filed. No new matter has been added. As claimed, the band region extends from the bonding region toward output side terminals of the substrate, the first regions are located on both sides of the bonding region, and the second region is located between the output side terminals and the first region.

This subject matter is specifically shown in Figure 1 of the application. Referring to Figure 1, the output side terminal are represented by numeral 4a. The band region is represented by numeral A3, and it can be seen that the band region extends from the bonding region (generally represented by numeral A2) towards the output side terminals

4a. With respect to the first regions being located on both sides of the bonding region, these regions are shown adjacent (i.e., to the left and right) of the bonding region A2. Lastly, with respect to the claimed second region, this region can be seen disposed on the right side of the substrate, between the first bonding region located to the right of the bonding region and the output side terminals 4a disposed at the upper portion of the substrate in Figure 1.

Uchiyama does not anticipate or render obvious such a configuration. That is, Uchiyama does not clearly specify a band region, as claimed. Further, assuming arguendo that Uchiyama does specify a band region, the claimed second region is located between the output side terminals and the first region. This is significant because the band region of the claimed invention is formed to be longer than any region taught by Uchiyama which allows enough space to be present on the substrate to mount the claimed second component. Since Uchiyama does not teach or suggest such a configuration, Applicants respectfully assert that new claims 33 and 34 are in condition for allowance.

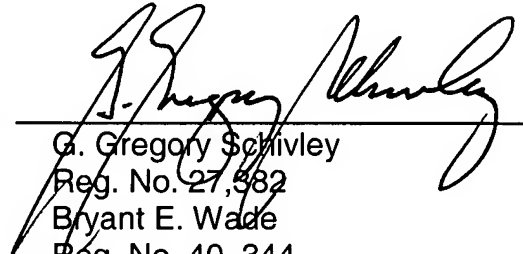
## **CONCLUSION**

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the

Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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